



# IC DRIVABLE PC BOARD **RELAY FOR INDUCTIVE** LOAD SWITCHING

# ST RELAYS



**RoHS Directive compatibility information** http://www.mew.co.jp/ac/e/environment/

# **FEATURES**

# 1. Even with small form factor, sensitive enough for direct IC-driving

The dimensions of this high-density 4gap balanced armature are 31 mm × 14 mm  $\times$  11 mm 1.220 inch  $\times$  .551 inch  $\times$ .433 inch. Despite this small size, high sensitivity is achieved by a mechanism that incorporates high-efficiency polarized magnetic circuits along with our exclusive spring alignment method. With an minimum operating power of about 150 mW, nominal operating power of 240 mW, this relay can be directly driven by

### 2. High switching capability

High contact pressure, low contact bounce, and forced separation structure that radically improves resistance to contact welding (1 Form A 1 Form B type equivalent to TV-3). Strong against lamp inductive loads, maximum switching capacity has reached 3,040 VA (8A 380V AC).

# 3. High breakdown voltage - Optimal for control in 250 V power circuits

High breakdown voltage has been achieved. Between contacts and coil of 3,750 Vrms; Surge breakdown voltage between coil and contact of 6,000 V, and between open contacts of 1,200 Vrms mean that these relays are suitable even for 250 V power circuit control.

## 4. Improved stability Conforms to all types of safety standards.

Insulating distance of more than 3 mm secured. Complies with Japan Electrical Appliance and Material Safety Law requirements for operating 200 V power supply circuits, and conforms with UL, CSA and VDE standards.

# 5. Latching types available

In addition to single side stable types, convenient 2 coil latching types with memory functions are also available. Moreover, we offer 2 Form A specifications which, with double pole switching for applications such as 250 V power circuit switching, can enable safer designs.

### 6. Automatic cleaning possible

The sealed design means that these relays can undergo immersion in automatic washing systems and are suitable for automatic soldering. Even in difficult environments, the contacts remain reliable.

# 7. Easy to design PC board patterns Features 4/10 dual-in-line terminals.

Because the lead spacing has a pitch greater than 7.54 mm .297 inch, designers can make easy adjustments with the width of the land size. This, along with the large insulation distance, simplifies the drawing of PC board patterns.

8. To improve soldering efficiency, preapplication of solder to the terminals is recommended.

### **About Cd-free contacts**

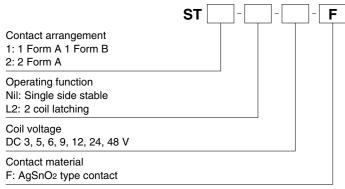
We have introduced Cadmium free type products to reduce Environmental Hazardous Substances.

(The suffix "F" should be added to the part number)

Please replace parts containing Cadmium with Cadmium-free products and evaluate them with your actual application before use because the life of a relay depends on the contact material and load.

# ORDERING INFORMATION

transistor or chip controllers.



Note: UL/CSA, VDE, SEV type is standard.

# **TYPES**

0	Name in all and to the ma	Single side stable	2 coil latching Part No.		
Contact arrangement	Nominal coil voltage	Part No.			
1 Form A 1 Form B	3V DC	ST1-DC3V-F	ST1-L2-DC3V-F		
	5V DC	ST1-DC5V-F	ST1-L2-DC5V-F		
	6V DC	ST1-DC6V-F	ST1-L2-DC6V-F		
	9V DC	ST1-DC9V-F	ST1-L2-DC9V-F		
	12V DC	ST1-DC12V-F	ST1-L2-DC12V-F		
	24V DC	ST1-DC24V-F	ST1-L2-DC24V-F		
	48V DC	ST1-DC48V-F	ST1-L2-DC48V-F		
2 Form A	3V DC	ST2-DC3V-F	ST2-L2-DC3V-F		
	5V DC	ST2-DC5V-F	ST2-L2-DC5V-F		
	6V DC	ST2-DC6V-F	ST2-L2-DC6V-F		
	9V DC	ST2-DC9V-F	ST2-L2-DC9V-F		
	12V DC	ST2-DC12V-F	ST2-L2-DC12V-F		
	24V DC	ST2-DC24V-F	ST2-L2-DC24V-F		
	48V DC	ST2-DC48V-F	ST2-L2-DC48V-F		

Standard packing: Tube: 50 pcs.; Case: 500 pcs.

# **RATING**

# Coil data Single side stable

Nominal coil voltage	Pick-up voltage (at 20°C 68°F)	Drop-out voltage (at 20°C 68°F)	Nominal operating current [±10%] (at 20°C 68°F)	Coil resistance [±10%] (at 20°C 68°F)	Nominal operating power	Max. allowable voltage (at 20°C 68°F)
3V DC	80%V or less of nominal voltage (Initial)		75mA	38Ω		
5V DC				105Ω		
6V DC		minal voltage nominal voltage	40mA	150Ω		150%V of nominal voltage
9V DC			25mA	360Ω	240mW	
12V DC			20mA	600Ω		
24V DC			10mA	2,400Ω		
48V DC			4.7mA	9,000Ω		

# 2) 2 coil latching

Nominal coil voltage	Set voltage (at 20°C 68°F)	Reset voltage (at 20°C 68°F)	Nominal operating current [±10%] (at 20°C 68°F)		Coil resistance [±10%] (at 20°C 68°F)		Nominal operating power		Max. allowable voltage (at 20°C 68°F)
· ·		,	Set coil	Reset coil	Set coil	Reset coil	Set coil	Reset coil	1
3V DC			75mA	75mA	40Ω	40Ω	240mW		150%V of nominal voltage
5V DC	80%V or less of nominal voltage (Initial)	voltage nominal voltage	45mA	45mA	110Ω	110Ω			
6V DC			37.5mA	37.5mA	155Ω	155Ω			
9V DC			25mA	25mA	360Ω	360Ω		240mW	
12V DC			18.8mA	18.8mA	640Ω	640Ω			
24V DC			10mA	10mA	2,400Ω	2,400Ω			
48V DC			4.7mA	4.7mA	10,200Ω	10,200Ω			

### 2. Specifications

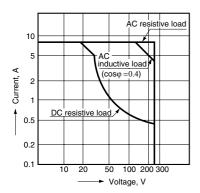
Characteristics		Item	Specifications			
	Arrangement		1 Form A 1 Form B, 2 Form A			
Contact	Contact material		Au-flashed AgSnO₂ type			
	Initial contact resistar	nce, max.	Max. 30 mΩ (By voltage drop 6 V DC 1A)			
D.	Max. switching power (resistive load)		3,040 VA, 150 W			
	Max. switching voltage		380 V AC, 250 V DC			
	Max. switching currer	nt	8 A			
ating	Minimum operating p	ower	150mW (Single side stable, 2 coil latching)			
	Nominal operating po	ower	240mW (Single side stable, 2 coil latching)			
	Min. switching capaci	ity (Reference value)*1	100 mA 5V DC			
	Insulation resistance (Initial) (at 25°C, 50% relative humidity)		Min. 1,000MΩ (at 500V DC) Measurement at same location as "Initial breakdown voltage" section.			
	Dun alledania valkana	Between open contacts	1,200 Vrms for 1 min. (Detection current: 10 mA)			
	Breakdown voltage (Initial)	Between contact sets	2,000 Vrms for 1 min. (Detection current: 10 mA)			
		Between contact and coil	3,750 Vrms for 1 min. (Detection current: 10 mA)			
lectrical	Surge breakdown vol	ltage (Initial)*2	6,000 V (Between contact and coil)			
characteristics	Operate time [Set time] (at 20°C 68°F)		Max. 15 ms [Max. 15 ms] (Nominal voltage applied to the coil, excluding contact bounce time.)			
	Release time [Reset time] (at 20°C 68°F)		Max. 10 ms [Max. 15 ms] (Nominal voltage applied to the coil, excluding contact bounce time.) (without diode)			
	Temperature rise (at 60°C 140°F)		Max. 55°C (By resistive method, nominal voltage applied to the coil; contact carrying current: 8A.)			
	Shock resistance	Functional	Min. 196 m/s <sup>2</sup> (Half-wave pulse of sine wave: 11 ms; detection time: 10μs.)			
1echanical		Destructive	Min. 980 m/s <sup>2</sup> (Half-wave pulse of sine wave: 6 ms.)			
haracteristics	Vibration resistance	Functional	10 to 55 Hz at double amplitude of 2 mm (Detection time: 10μs.)			
	VIDIALION TESISLANCE	Destructive	10 to 55 Hz at double amplitude of 3 mm			
Expected life	Mechanical		Min. 10 <sup>7</sup> (at 180 cpm)			
	Electrical		Min. 10 <sup>5</sup> (8 A 250 V AC resistive) (ON : OFF = 1 s : 5 s)			
Conditions	Conditions for operat	ion, transport and storage*3	Ambient temperature: -40°C to +60°C -40°F to +140°F; Humidity: 5 to 85% R.H. (Not freezing and condensing at low temperature)			
	Max. operating speed		30 cps			
Jnit weight			Approx. 10g .353 oz			

Notes: \*1 This value can change due to the switching frequency, environmental conditions, and desired reliability level, therefore it is recommended to check this with the actual load.

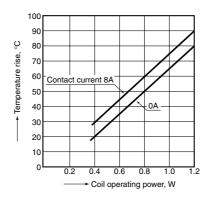
- \*2 Wave is standard shock voltage of ±1.2×50μs according to JEG-212-1961
  \*3 Refer to 6. Conditions for operation, transport and storage mentioned in AMBIENT ENVIRONMENT

# **REFERENCE DATA**

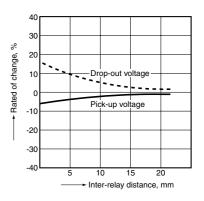
# 1. Max. switching power



# 2. Coil temperature rise

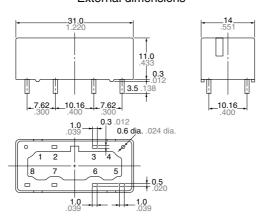


# 3. Influence of adjacent mounting

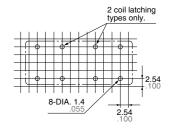


# **DIMENSIONS** (Unit: mm inch)

### External dimensions



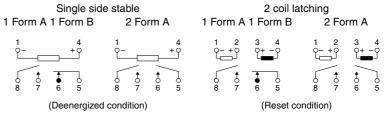
# PC board pattern (Bottom view)



Tolerance: ±0.1 ±.004

General tolerance: ±0.5 ±.020

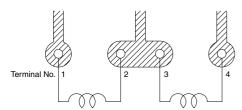
## Schematic (Bottom view)



# **NOTES**

# 1. PC board patterns for 2 coil latching types

When applying relays in power supply operation circuits for finished products regulated by the Electrical Appliance and Material Safety Law, use the pattern shown below.



# 2. Soldering should be done under the following conditions:

1) 250°C 482°F within 10s 300°C 572°F within 5s 350°C 662°F within 3s

2) For automatic cleaning, the boiling method is recommended. Avoid ultrasonic cleaning which subjects the relays to high frequency vibrations, which may cause the contacts to stick. It is recommended that a fluorinated hydrocarbon or other alcoholic solvents be used.

3. When using, please be aware that the a contact and b contact sides of 1 Form A and 1 Form B types may go on simultaneously at operate time and release time.

# For Cautions for Use, see Relay Technical Information.



# **Panasonic** ideas for life

# **ACCESSORIES**

ST relay socket



PC board terminal socket



ST-SS Solder terminal socket

**RoHS Directive compatibility information** http://www.mew.co.jp/ac/e/environment/

# **FEATURES**

- 1. Possible to fit or remove the chassis with one touch (t = 0.6 mm to 2.2 mm .024 inch to .087 inch)
- 2. Easy design of PC board pattern (2.54 mm x 4 pitch DIL terminal array)

3. Complies with Japan Electrical Appliance and Material Safety Law.

(UL and VDE certification)

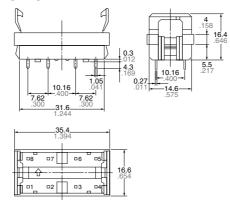
# 4. High breakdown voltage.

# **SPECIFICATIONS**

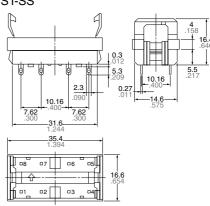
Item	Specifications			
Breakdown voltage (Initial)	Between contact and coil: 4,000 Vrms for 1 min. (Detection current: 10 mA) Between contact and terminal: 2,000 Vrms for 1 min.			
Insulation resistance (Initial)	Min. 1,000 MΩ between terminals (500V DC)			
Heat resistance	150°C 302°F for 1 hr			
Max. continuous current	10 A			
Relay insertion life	15 times			

# **DIMENSIONS** (Unit: mm inch)

ST-PS

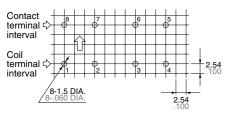


# ST-SS



# PRECAUTIONS FOR USE (SOCKET)

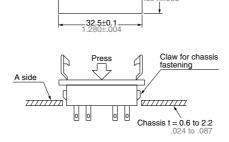
# 1. PC board mounting method PC board pattern



The terminal configuration is symmetrical on the left and right, so an arrow mark 1 is stamped on the socket to prevent misinsertion. We recommend printing the same arrow mark  $\bigcirc$  on the component mounting side (side opposite from pattern) of the PC board. In this case, the terminal configuration becomes the terminal nos. noted near the drilling holes.

### 2. Chassis cutout

Chassis cutting dimensions



15.0±0.2

If the chassis hole is punched with a press, set so the release R on the front side (A side).

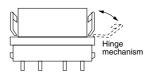
The range for chassis thickness is 0.6 to 2.2 mm .024 to .087 inch.

# 3. Relay mounting and removal

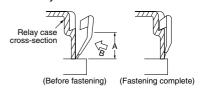
(1) Align the directions of the relay and socket.



(2) Insert the relay all the way in, so it is securely in place.



(3) Press the part indicated by A in the B direction, and fasten by placing the hook on the relav.



(4) When removing the relay, completely release the hooks on both sides and pull the relay out.